# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP Pavilion Power Laptop PC 15 (Touch)

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base screws 7pcs.
2. Disassemble base cover from the unit.
3. Take off 4 pcs of screws which fastening battery to Top Assy. and then disassemble the Battery.
4. Remove HDD and HDD cable.
5. Remove KB BL FFC, KB FFC, TP FFC, LCD cable's MB side, Antenna cable's MB side, DB to MB FFC and P/B to DB FFC.
6. Remove 2 pcs of screws and disassemble DB.
7. Remove 6pcs of screws and disassemble the display unit from top-assy.
8. Loose 1 pcs of screw which fastening P/B and take it off from top-assy.
9. Remove K-lock bkt from top-assy.
10. Remove 6 pcs of screws and disassemble thermal module.
11. Lose 5pcs screws and remove fan cables and 2 fans.
12. Loose 3pcs screws whiching fastening MB on top_assy and take MB off from top-assy.
13. Remove 1 pcsscew and disassemble Wlan module from MB.
14. Remove 1 pcsscew and disassemble SSD module from MB.
15. Remove DC-in cable, DB to MB FFC from MB.
16. Remove RAM module and RTC battery from MB.
17. Disassemble speaker R and L from top-assy.
18. Loose 3pcs screws whiching fastening TP support on top-assy and take off TP support BKT from top-assy.
19. Loose 3pcs screws whiching fastening TP and TP holder assy and take this assy from top-assy.
20. Disassemble LCD bezel from display unit.
21. Remove hinge cap R and L from display unit.
22. Loose 4 pcs of screws which fasetening LCD module from cover and take it off from LCD cover. Before removing LCD module, separate LCD cable from LCD module.
23. Loose 4 pcs of screws which fasetening Hinge R from LCD cover and remove hinge R from LCD cover.
24. Loose 4 pcs of screws which fasetening Hinge L from LCD cover and remove hinge L from LCD cover.
25. Separate LCD cable from camera module and remove both from LCD cover.
26. Remove antenna cable from LCD cover.
27. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

PSG instructions for this template are available at EL-MF877-01
3.22 Remove base cover.

3.23 Remove Battery

3.24 DB and HDD assy
3.25 Display unit

3.26 P/B and K-lock BKT

3.27 Thermal module and Fan

3.28 MB, Wlan module and SSD module

PSG instructions for this template are available at EL-MF877-01
3.29 DC-IN CABLE and DB to MB FFC from MB.

3.30 Ram, Speaker R & L.
3.31 TP support BKT and TP holder asy.

3.32 LCD Bezel

3.33 Hinge cap R & L
3.34 LCD cover and LCD module

3.35 Hinge R and L

3.36 LCD cable, Antenna cable and Camera module
PSG instructions for this template are available at EL-MF877-01